Formation of a Quasi-Periodic Copper Thin Film

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We have synthesised a thin film of copper with a quasi-periodic structure by the adsorption of copper atoms on the five-fold surface of the icosahedral quasicrystal Al-Pd-Mn at room temperature. The quasi-periodicity of the thin film is manifested in low energy electronic diffraction (LEED) measurements and in the existence of Fibonacci relationships between rows of copper atoms imaged using scanning tunneling microscopy (STM). These findings demonstrate the feasibility of single-element quasi-periodic thin film formation using quasicrystals as templates.

Copper is one of the oldest elements known to mankind and it crystallizes in a face-centred cubic structure. Quasicrystals are a relatively new form of matter, first reported in 1984[1], and are bi- and tri-metallic alloys with long-range order but no translational symmetry. In the course of investigations aimed at understanding the interactions between quasicrystal surfaces and adsorbed atomic and molecular species[2], we have discovered that the adsorption of Cu on the five-fold surface of the icosahedral quasicrystal Al-Pd-Mn at 300 K leads to the formation of a quasi-periodic Cu thin film. The quasi-periodic structure of the thin film is manifested in low energy electronic diffraction (LEED) measurements and in the existence of Fibonacci relationships between rows of Cu atoms on the surface imaged using scanning tunneling microscopy (STM). The ability to synthesise such single-element quasi-periodic thin films will facilitate the study of the relationship between quasi-periodicity and physical properties and enable the probing of the transition from two-dimensional (2D) to three-dimensional (3D) electronic properties in a quasi-periodic material.

The starting point in these investigations is the preparation of high quality clean surfaces of Al-Pd-Mn with large flat terraces (microns in size) and low surface corrugation in an ultra-high-vacuum (UHV) environment. The methodology for the preparation of these surfaces has been previously described in detail[3,4] and consists of ex-situ polishing followed by several cycles of ion sputtering (1 hour) and annealing to 940 K (4 hours) with a cumulative anneal time of 20 hours. Surface preparation is facilitated using LEED to establish the degree of surface ordering and Auger electron spectroscopy (AES) to check for contamination (and later to monitor Cu deposition). Surfaces prepared in this manner have been shown to be essentially ideal terminations of the bulk quasicrystal structure[3,5], and the 2D structure of these surfaces has been described as a Fibonacci pentagrid[6], with the five principal symmetry axes evident in the arrangement of the dominant structural motifs. This is illustrated in Fig. 1(a) which shows a high resolution STM image of a small area (10 nm x 10 nm) of such a surface. Several groupings of atoms with five-fold and ten-fold symmetry are evident. The dark five-fold stars are Bergman clusters (a basic structural entity of this type of quasicrystal) which have been truncated in the surface formation process[4]. White lines drawn on the figure join identical positions on the dark five-fold stars; the separations between the lines are of two lengths $L = 0.74 \pm 0.02$ nm and $S = 0.46 \pm 0.02$ nm, whose ratio is within experimental error equal to the golden mean τ [τ is the irrational number expected for the ratio of the two basic units of the Fibonacci sequence [$\tau = (\sqrt{5}+1)/2 = 1.618\ldots$]. Furthermore the arrangement of these line separations (reading from bottom to top) LSLLSL forms a segment of the Fibonacci sequence.

Deposition of Cu atoms on the surface was achieved using a simple evaporation source consisting of a tantalum filament which was wrapped around a sample of pure Cu. The filament was thoroughly degassed before evaporation and the evaporation flux was found to be very consistent under constant conditions of the control parameters. The experiments were conducted using a Cu flux of $4.5 \pm 0.2 \times 10^{-2}$ monolayers s^{-1} as determined by measuring the fractional area of the surface covered with successive Cu depositions. The sample was at room temperature during deposition and measurement.

Figure 2 gives an overview of the growth of Cu on the surface at room temperature for increasing Cu coverage. Under the above deposition conditions the growth of Cu on the Al-Pd-Mn surface is observed to proceed in a layer-by-layer manner. The step height from layer to layer is 0.19 ± 0.01 nm. For sub-monolayer coverages (Fig. 2(a))

Cu islands form on the surface and as adsorption continues the second layer is observed to begin growing when the first layer is 90 5% complete. For layers 1 to 4 the Cu atoms within the layers are observed to self-organise into small domains within which there is a developing pattern of one-dimensional rows (Fig 2(b)). From layers 5 to 8 a very well-developed row structure is observed (Fig. 2(c)). From layer 9 the effect of layer growth before previous layer completion becomes more marked as shown in Fig. 2(d); this results in a diminishing domain size and in the simultaneous existence of many incomplete layers at the surface. The row structure persists in these layers. The results were reproduced several times and the growth was monitored up to the 25th. layer.

Fig. 3(a) is a 40nm x 40 nm image taken during the growth of the 6th layer. This image reveals several intriguing details. The islands have sharp edges where the border is a single row. A plausible explanation for the growth mechanism is the initial adsorption of Cu on top of a growing layer, followed by diffusion of the adsorbed atoms along the Cu rows and subsequent attachment at the end of each row. The rows themselves appear in five orientations, with the angles made by intersections of rows in the same layer corresponding to the internal angles of a pentagon. The intersections between rows are of two types. Two sets of rows can meet at vertex points, where the end of each row in one direction meets the end of another at an angle of 108° (the internal angle of a pentagon). Alternatively the rows in one direction intersect a single row at an angle of 72°. The rows do not form a periodic structure.

The corrugation across the rows is measured at 0:025 0:005 nm using STM. The atomic structure within the rows is not resolved in these experiments; this could be an indication of a large vibrational amplitude along the rows; alternatively it could reflect a low corrugation in electronic density along the rows. The fact that the LEED pattern shows discrete spots is indicative of long-range order both within and across domains and along the rows themselves. The row directions are also observed to be correlated from layer to layer, indicating that each layer acts as a template for the subsequent one in the growth process.

The inter-row distances form aperiodic sequences having long and short separations. This is illustrated in Figure 4 which shows a 10 nm x 10 nm image of the surface during formation of the 6th layer. There are some vacancy defects in the rows themselves. Nevertheless sequences of rows having S and L separations are visible. The average spacings are measured at 0:45 0:02 nm and L = 0:73 0:03 nm. The ratio of these numbers equals the golden mean within experimental error. Two such sequences (SLLSLSL, reading from bottom to top) are indicated on this figure, on rows which meet at vertex points. This indicates that the same sequencing information is common to both sets of rows. The coherence length of the row structures appears to be determined by the domain walls which arise during the growth process. The close match of these row spacings in the Cu structure with those illustrated for the clean surfaces (Figure

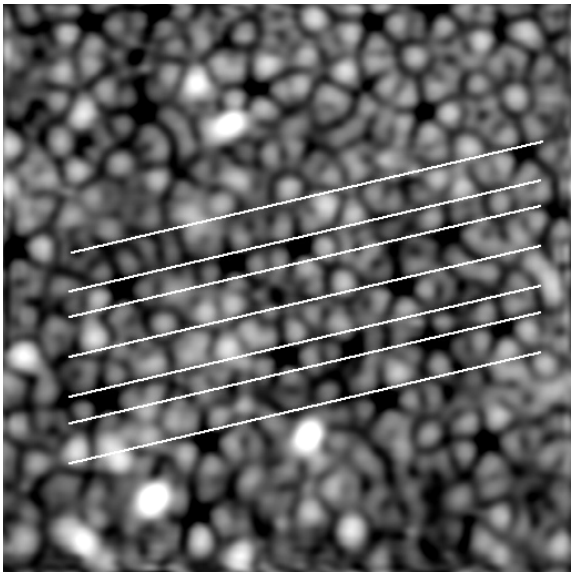

FIG. 1: 10 nm x 10 nm STM image of the five-fold surface of Al-Pd-Mn. The lines join identical positions on the dark five-fold stars; the separations between the lines are of two lengths L = 0:74 0:02 nm and S = 0:46 0:02 nm, whose ratio is within experimental error equal to the golden mean ; furthermore the arrangement of these line separations (from bottom to top) LSLLSL forms a segment of the Fibonacci sequence.

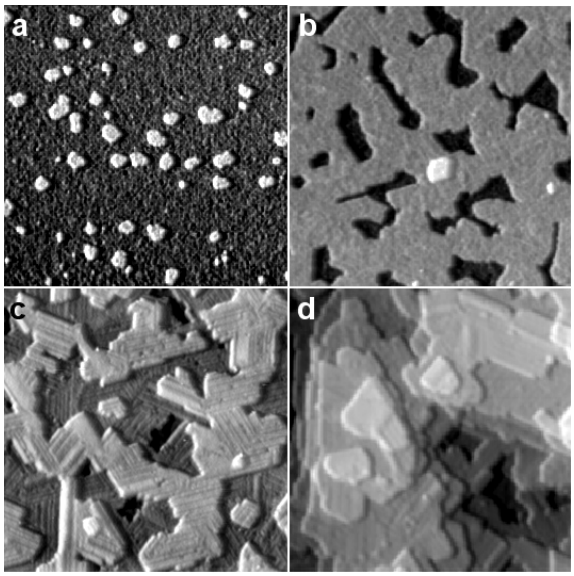

FIG. 2: (a) 50 nm x 50 nm STM snapshots of the five-fold surface of Al-Pd-Mn during the growth of the Cu thin film. (a) 0.09 layers of Cu, (b) 3.8 layers, (c) 5.5 layers, (d) 11.7 layers.

1) indicate that the clean surfaces acts as a template for the ordered growth of the Cu atoms.

The LEED pattern characteristic of this layered row structure is shown in Fig. 3(b). The pattern has ten-fold symmetric rings of spots whose distances from the central spot (hidden by the electron gun in the Figure) exhibit a -scaling relationship. From layers 9 to 20, with the simultaneous growth of multiple layers, the LEED pattern becomes streaky and diffuse and eventually degrades and disappears by the 25th layer. This is consistent with the diminishing domain size.

Upon annealing to 570 K, STM images (not shown) reveal that the Cu thin film undergoes an irreversible transformation to a cubic structure Cu with five domains rotated from each other by 72°. The LEED pattern associated with this phase, although 10-fold symmetric, no longer has the -scaling relationships in the distances of the diffraction spots. The domain boundaries of this phase are decorated with excess Cu atoms. Flashing the sample to 660 K results in thermal desorption of the Cu film and the clean surface LEED pattern is restored.

There has been a report of the use of these surfaces for the growth of five-fold symmetric nanoclusters[7] by the adsorption of sub-monolayer amounts of aluminum on Al-Cu-Fe. There has been a report of ordered atomic Si and B monolayers on quasicrystal surfaces[8], and another report of the formation of a quasicrystalline bi-metallic Au-Al alloy by deposition and subsequent annealing of a Au film on an Al-Pd-Mn substrate[9]. In other work, the deposition of Ag at low temperature onto to a GaAs(110) substrate followed by annealing to room temperature was found to form a Ag (111) film with a surface quasiperiodic modulation[10,11]. However the system described in this report is unique in that it constitutes a single element quasi-periodic thin film grown using a quasicrystal surface as a template.

The quasi-periodicity of the film, together with the one-dimensionality of the row structure, suggest the possibility of unusual vibrational and electronic properties in this system. The well-documented low density of electronic states at the Fermi level in the bulk quasicrystal (the so-called pseudogap) means features in the va-

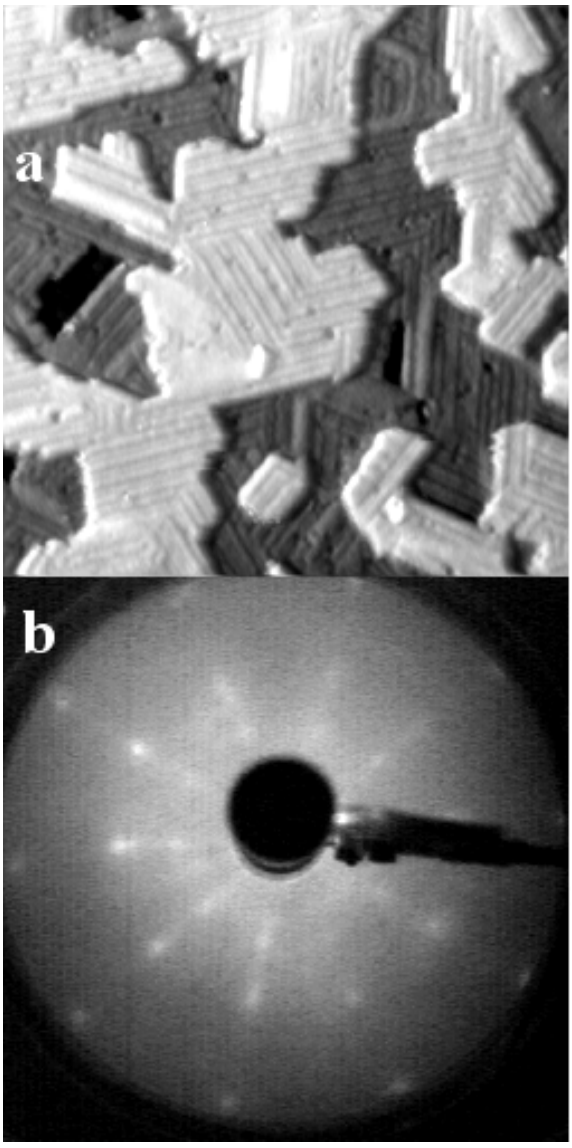

FIG. 3: (a) 40 nm x 40 nm STM image of the five-fold surface of Al-Pd-Mn after deposition of 5.5 ML of Cu. (b) LEED pattern (beam energy 50 eV) corresponding to this phase. The relationships between spot positions are indicative of -scaling within experimental error.

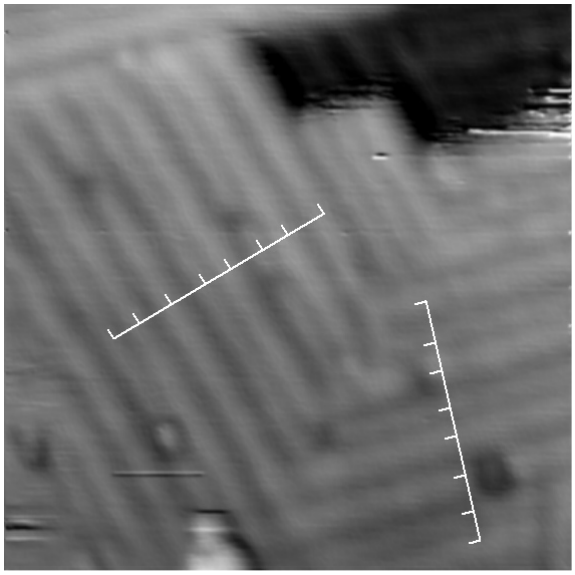

FIG. 4: (a) 10 nm x 10 nm STM image of the five-fold surface of Al-Pd-Mn. The lines marks sequences of Cu rows with spacings given by SLLSLSL (from bottom to top). The spacings are S = 0:45 0:02 nm and L = 0:73 0:03 nm. The ratio of these numbers equals the golden mean within experimental error.

lence electronic structure of the Cu film should be readily distinguishable from those of the substrate. This system also offers interesting possibilities for monitoring the transition from 2D to 3D electronic properties in a quasi-periodic material as the thickness of the film is increased, and for probing the relationship between quasi-periodicity and physical properties. The surface of the film itself has the potential to act as an adsorption template for the formation of further quasi-periodic systems. Furthermore we have no reason to believe that the Cu/Al-Pd-Mn system is unique; we anticipate the discovery of further aperiodic thin film systems, with the promise of new electronic and/or magnetic properties.

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